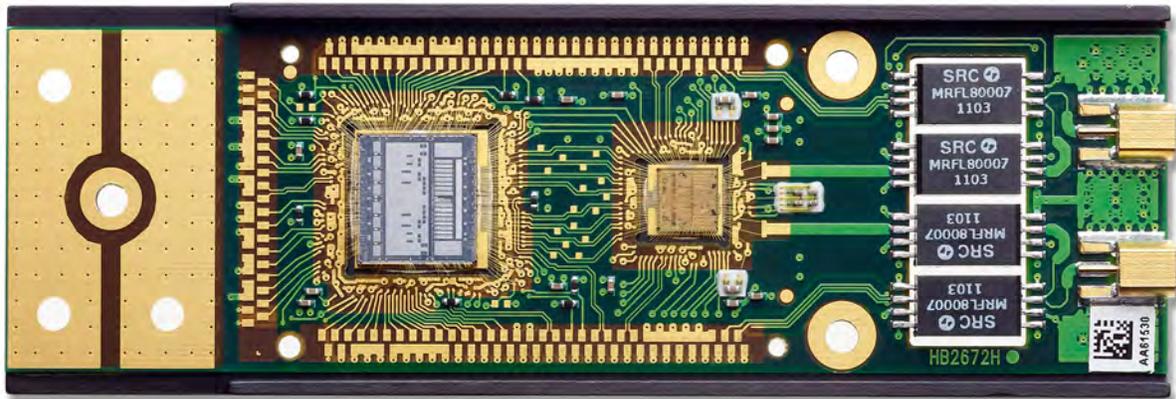


IC Packaging Services

Delivering Turnkey Packaging Services to Ensure Performance, Reliability and Quality in Complex Microelectronics



Tektronix Component Solutions offers turnkey IC packaging services for custom, high-performance microelectronics. This includes a full range of design, lean manufacturing and test services for a variety of applications. Customizable 15 and 30+ GHz BGA and 40 GHz Leadless Chip Carrier (LCC) packaging platforms are also available to meet your wide bandwidth needs.

Design

With an experienced, in-house engineering team, Tektronix Component Solutions offers package design, simulation and analysis services for high-performance applications. Focusing on manufacturability and testability, packages are designed to meet your specific requirements for signal integrity, performance and high-reliability.

Assembly

All parts are built at Tektronix Component Solutions' US-based manufacturing facility, which supports volumes ranging from a few hundred to 100,000 units per year. With 18 lean cells spread throughout 32,000 square feet of Class 10K clean-room, the organization can cost-effectively assemble devices ranging from single-IC packages to multi-chip and electro-optical modules. Additionally, as a RoHS compliance capable supplier, Tektronix Component

Solutions can develop packaging solutions that meet specific materials usage requirements. Rapid prototyping services are also available for faster validation of IC and package designs, speeding the transition to full production.

Test

As a strategic part of Tektronix for more than 40 years, Tektronix Component Solutions has developed a unique strength in test. Wafer testing services from Tektronix Component Solutions improve die yield before assembly into a package, thereby reducing scrap cost. Analog, digital and mixed-signal testing capabilities (in-line or final test) are also offered to ensure each unique component achieves its performance goals.

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Package Technologies

Tektronix Component Solutions' advanced package development services optimize critical performance parameters such as signal speed and integrity, while controlling other parameters such as temperature. A key design challenge is to select the appropriate packaging technology while managing any resulting design tradeoffs. Our ability to draw from a broad base of packaging and assembly technologies is a key factor in optimizing your components.

- Ball Grid Array (BGA)
- Leadless Chip Carrier (LCC)
- Chip-on-Board (COB)
- Chip-on-Flex (COF)
- Multi-chip Module (MCM) / System-in-Package (SIP)
- Hybrids & mixed technology

Interconnect Technologies

Selecting the appropriate interconnect technology is a key consideration in optimizing your IC package. Interconnect choice can directly impact package characteristics such as signal speed, signal integrity, and cost, size, weight and power (C-SWaP). Tektronix Component Solutions has capabilities in a variety of interconnect technologies and can help select the appropriate interconnect as part of the design and manufacture of your device.

- Flip chip interconnect
- Wire-bond interconnect
 - Ball-stitch (thermosonic)
 - Ball-stitch (thermocompression)
 - Wedge (thermosonic)
 - Wedge (ultrasonic)
- Optical interconnect

Certifications & Compliance

- ISO9001:2008
- ISO14001:2004
- ITAR-registered
- Category 1A Trusted Supplier
- RoHS-compliance capable

Contact our experienced team to discuss your application and IC package needs:

800-462-9835 | components@tektronix.com

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